

# Vyncolit® TEM 9053

Epoxy; Epoxide

Vyncolit N.V.

## Message:

TEM 9053 is a short fiberglass and mineral filled, toughened, epoxy molding compound, with excellent dimensional stability and high strength properties.

General Information			
Filler / Reinforcement	Glass \Mineral		
Features	Good dimensional stability		
	The degassing effect is low to no		
	Low viscosity		
	High strength		
	Solvent resistance		
	Anti-salt water/fog		
	Good thermal shock resistance		
	Good chemical resistance		
	alkali resistance		
	acid resistance		
	Good toughness		
	Non-corrosive		
Uses	Electrical components		
	Military application		
	Connector		
Agency Ratings	FDA not rated		
	USDA Unspecified Approval		
Appearance	Black		
Forms	Particles		
Processing Method	Resin transfer molding		
	Compression molding		
	Injection molding		
Physical	Nominal Value	Unit	Test Method
Specific Gravity	1.95	g/cm³	ASTM D792
Molding Shrinkage - Flow (Compression Molded)	0.25	%	ASTM D955
Hardness	Nominal Value	Unit	Test Method
Rockwell Hardness (M-Scale)	70		ASTM D785

Mechanical	Nominal Value	Unit	Test Method
Tensile Strength (Break, Compression Molded)	97.0	MPa	ASTM D638
Flexural Modulus (Compression Molded)	16600	MPa	ASTM D790
Flexural Strength (Break)	160	MPa	ASTM D790
Compressive Strength	235	MPa	ASTM D695
Impact	Nominal Value	Unit	Test Method
Notched Izod Impact (Compression Molded)	24	J/m	ASTM D256
Thermal	Nominal Value	Unit	Test Method
Deflection Temperature Under Load (1.8 MPa, Unannealed, Compression Molded)	160	°C	ASTM D648
CLTE - Flow	2.6E-5	cm/cm/°C	ASTM E831
Thermal Conductivity	0.71	W/m/K	ASTM C177
Electrical	Nominal Value	Unit	Test Method
Dielectric Strength <sup>1</sup>	13	kV/mm	ASTM D149
Dielectric Constant (1 MHz)	4.20		ASTM D150
Dissipation Factor (1 MHz)	0.015		ASTM D150
Arc Resistance	180	sec	ASTM D495
Injection	Nominal Value	Unit	
Middle Temperature	60.0 - 82.2	°C	
Nozzle Temperature	82.2 - 93.3	°C	
Processing (Melt) Temp	93.3 - 116	°C	
Mold Temperature	149 - 177	°C	
Injection Pressure	34.5 - 68.9	MPa	
Holding Pressure	13.8 - 34.5	MPa	
Back Pressure	0.345	MPa	
Injection instructions			
Gauge: 0.3The value listed as Thermal Conductivity, ASTM C177, was tested in accordance with ASTM C518.Powder Density, ASTM D1895: 0.85 g/cm <sup>3</sup> Water Absorption, ASTM D570, 48 hrs, 50°C: 0.23%DTUL @264psi - Unannealed, ASTM D648, Post Baked, Compression Molded: 160°CDielectric Strength, ASTM D149, 60 Hz, Method B, wet: 12.8 kV/mmDielectric Constant, ASTM D150, 1000000 Hz, wet: 4.2Dissipation Factor, ASTM D150, 1000000 Hz, wet: 0.015Compression and Transfer Molding Conditions: Preheat Temperature: 180 to 225 °F Mold Temperature: 325 to 370 °F Compression Mold Pressure: 1000 to 5000 psi Transfer Mold Pressure: 1500 to 8000 psi Cure Time, 0.125 in: 60 to 90 sec			
NOTE			
1.	Method B (step by step)		

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